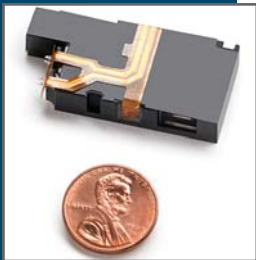
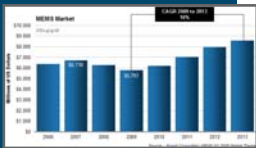
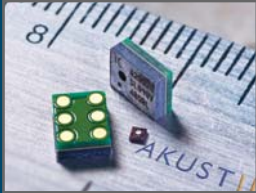


# Advanced Packaging Update: Market and Technology Trends

Vol. 1, 2009



Volume 1 of the Advanced Packaging Update for 2009 features an update on industry and economic trends for the semiconductor packaging and assembly industry focusing on packaging trends that are driving growth. An analysis of the 300mm wafer level packaging capacity shortage is provided. A special section is devoted to recent developments in embedded components. An in-depth MEMS packaging update is also included, with special focus on microphones, micro-mirror projectors, RF MEMS, and future medical MEMS. New package developments and trends are also discussed, including increasing concerns about alpha particle emissions in packaging materials and the impact on reliability in high-performance applications.

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Annual subscription – \$3,425 (4 issues)  
Single issue – \$975

  
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